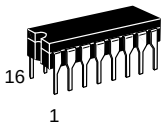
MC54/74HC161A
MC54/74HC163A

Presettable Counters
High–Performance Silicon–Gate CMOS

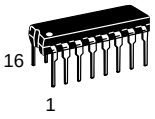
The MC54/74HC161A and HCI63A are identical in pinout to the LS161 and LS163. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC161A and HC163A are programmable 4–bit binary counters with asynchronous and synchronous reset, respectively.

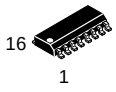
- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 192 FETs or 48 Equivalent Gates



J SUFFIX
CERAMIC PACKAGE
CASE 620–10



N SUFFIX
PLASTIC PACKAGE
CASE 648–08

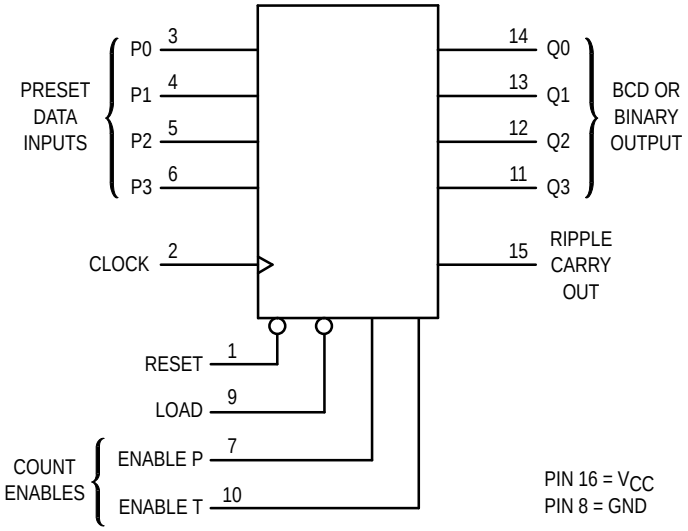


D SUFFIX
SOIC PACKAGE
CASE 751B–05

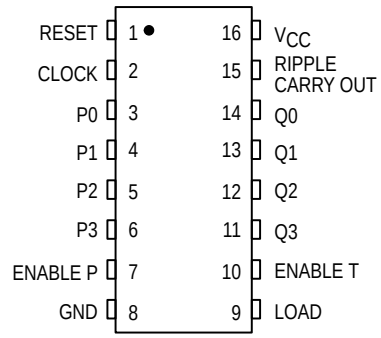
ORDERING INFORMATION

MC54HCXXXAJ	Ceramic
MC74HCXXXAN	Plastic
MC74HCXXXAD	SOIC

LOGIC DIAGRAM



PIN ASSIGNMENT



Device	Count Mode	Reset Mode
HC161A	Binary	Asynchronous
HC163A	Binary	Synchronous

FUNCTION TABLE

Inputs					Output
Clock	Reset*	Load	Enable P	Enable T	Q
↗	L	X	X	X	Reset
↗	H	L	X	X	Load Preset Data
↗	H	H	H	H	Count
↗	H	H	L	X	No Count
↗	H	H	X	L	No Count

* HC163A only. HC161A is an Asynchronous Reset Device
H = high level
L = low level
X = don't care

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	– 0.5 to + 7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	– 1.5 to V_{CC} + 1.5	V
V_{out}	DC Output Voltage (Referenced to GND)	– 0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA
P_D	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package†	750 500	mW
T_{stg}	Storage Temperature	– 65 to + 150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package) (Ceramic DIP)	 260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

* Maximum Ratings are those values beyond which damage to the device may occur.
Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C
Ceramic DIP: – 10 mW/°C from 100° to 125°C
SOIC Package: – 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0	V_{CC}	V
T_A	Operating Temperature, All Package Types		– 55	+ 125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	V_{CC} = 2.0 V V_{CC} = 4.5 V V_{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				– 55 to 25°C	≤ 85°C	≤ 125°C	
V_{IH}	Minimum High–Level Input Voltage	V_{out} = 0.1 V or V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V_{IL}	Maximum Low–Level Input Voltage	V_{out} = 0.1 V or V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 μA	2.0 4.5 6.0	0.50 1.35 1.80	0.50 1.35 1.80	0.50 1.35 1.80	V
V_{OH}	Minimum High–Level Output Voltage	V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 4.0 mA $\|I_{out}\|$ ≤ 5.2 mA	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	V
V_{OL}	Maximum Low–Level Output Voltage	V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 20 μA	2.0 4.5 6.0	0.10 0.10 0.10	0.10 0.10 0.10	0.10 0.10 0.10	V
		V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 4.0 mA $\|I_{out}\|$ ≤ 5.2 mA	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	V
I_{in}	Maximum Input Leakage Current	V_{in} = V_{CC} or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	V_{in} = V_{CC} or GND I_{out} = 0 μA	6.0	4	40	160	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input $t_r = t_f$ = 6.0 ns)

Symbol	Parameter	Fig.	V_{CC} V	Guaranteed Limit			Unit
				– 55 to 25°C	≤ 85°C	≤ 125°C	
f_{max}	Maximum Clock Frequency (50% Duty Cycle)*	1, 7	2.0 4.5 6.0	6 30 35	5 24 28	4 20 24	MHz
t_{PLH}	Maximum Propagation Delay, Clock to Q	1, 7	2.0 4.5 6.0	120 20 16	160 23 20	200 28 22	ns
t_{PHL}		1, 7	2.0 4.5 6.0	145 22 18	185 25 20	320 30 23	ns
t_{PHL}	Maximum Propagation Delay, Reset to Q (HC161A Only)	2, 7	2.0 4.5 6.0	145 20 17	185 22 19	220 25 21	ns
t_{PLH}	Maximum Propagation Delay, Enable T to Ripple Carry Out	3, 7	2.0 4.5 6.0	110 16 14	150 18 15	190 20 17	ns
t_{PHL}		3, 7	2.0 4.5 6.0	135 18 15	175 20 16	210 22 20	ns
t_{PLH}	Maximum Propagation Delay, Clock to Ripple Carry Out	1, 7	2.0 4.5 6.0	120 22 18	160 27 22	200 30 25	ns
t_{PHL}		1, 7	2.0 4.5 6.0	145 22 20	185 28 24	220 35 28	ns
t_{PHL}	Maximum Propagation Delay, Reset to Ripple Carry Out (HC161A Only)	2, 7	2.0 4.5 6.0	155 22 18	190 26 22	230 30 25	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output	2, 7	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{in}	Maximum Input Capacitance	1, 7	—	10	10	10	pF

* Applies to noncascaded/nonsynchronous clocked configurations only with synchronously cascaded counters. (1) Clock to Ripple Carry Out propagation delays. (2) Enable T or Enable P to Clock setup times and (3) Clock to Enable T or Enable P hold times determine f_{max}. However, if Ripple Carry out of each stage is tied to the Clock of the next stage (nonsynchronously clocked) the f_{max} in the table above is applicable. See Applications information in this data sheet.

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V_{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Gate)*	30	pF

* Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS (C_L = 50 pF, Input $t_r = t_f$ = 6.0 ns)

Symbol	Parameter	Fig.	V_{CC} V	Guaranteed Limit			Unit
				– 55 to 25°C	≤ 85°C	≤ 125°C	
t_{su}	Minimum Setup Time, Preset Data Inputs to Clock	5	2.0 4.5 6.0	40 15 12	60 20 18	80 30 20	ns
t_{su}	Minimum Setup Time, Load to Clock	5	2.0 4.5 6.0	60 15 12	75 20 18	90 30 20	ns
t_{su}	Minimum Setup Time, Reset to Clock (HC163A Only)	4	2.0 4.5 6.0	60 20 17	75 25 23	90 35 25	ns
t_{su}	Minimum Setup Time, Enable T or Enable P to Clock	6	2.0 4.5 6.0	80 20 17	95 25 23	110 35 25	ns
t_h	Minimum Hold Time, Clock to Load or Preset Data Inputs	5	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t_h	Minimum Hold Time, Clock to Reset (HC163A Only)	4	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t_h	Minimum Hold Time, Clock to Enable T or Enable P	6	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock (HC161A Only)	2	2.0 4.5 6.0	80 15 12	95 20 17	110 26 23	ns
t_{rec}	Minimum Recovery Time, Load Inactive to Clock	5	2.0 4.5 6.0	80 15 12	95 20 17	110 26 23	ns
t_w	Minimum Pulse Width, Clock	1	2.0 4.5 6.0	60 12 10	75 15 13	90 18 15	ns
t_w	Minimum Pulse Width, Reset (HC161A Only)	2	2.0 4.5 6.0	60 12 10	75 15 13	90 18 15	ns
t_r, t_f	Maximum Input Rise and Fall Times		2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

FUNCTION DESCRIPTION

The HC161A/163A are programmable 4–bit synchronous counters that feature parallel Load, synchronous or asynchronous Reset, a Carry Output for cascading and count–enable controls.

The HC161A and HC163A are binary counters with asynchronous Reset and synchronous Reset, respectively.

INPUTS

Clock (Pin 2)

The internal flip–flops toggle and the output count advances with the rising edge of the Clock input. In addition, control functions, such as resetting and loading occur with the rising edge of the Clock input.

Preset Data Inputs P0, P1, P2, P3 (Pins 3, 4, 5, 6)

These are the data inputs for programmable counting. Data on these pins may be synchronously loaded into the internal flip–flops and appear at the counter outputs. P0 (Pin 3) is the least–significant bit and P3 (Pin 6) is the most–significant bit.

OUTPUTS

Q0, Q1, Q2, Q3 (Pins 14, 13, 12, 11)

These are the counter outputs. Q0 (Pin 14) is the least–significant bit and Q3 (Pin 11) is the most–significant bit.

Ripple Carry Out (Pin 15)

When the counter is in its maximum state 1111, this output goes high, providing an external look–ahead carry pulse that may be used to enable successive cascaded counters. Ripple Carry Out remains high only during the maximum count state. The logic equation for this output is:

$$\text{Ripple Carry Out} = \text{Enable T} \bullet Q0 \bullet Q1 \bullet Q2 \bullet Q3$$

CONTROL FUNCTIONS

Resetting

A low level on the Reset pin (Pin 1) resets the internal flip–flops and sets the outputs (Q0 through Q3) to a low level. The HC161A resets asynchronously, and the HC163A resets with the rising edge of the Clock input (synchronous reset).

Loading

With the rising edge of the Clock, a low level on Load (Pin 9) loads the data from the Preset Data input pins (P0, P1, P2, P3) into the internal flip–flops and onto the output pins, Q0 through Q3. The count function is disabled as long as Load is low.

Count Enable/Disable

These devices have two count–enable control pins: Enable P (Pin 7) and Enable T (Pin 10). The devices count when these two pins and the Load pin are high. The logic equation is:

$$\text{Count Enable} = \text{Enable P} \bullet \text{Enable T} \bullet \text{Load}$$

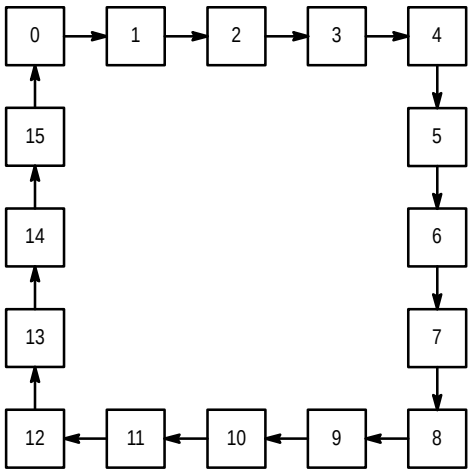
The count is either enabled or disabled by the control inputs according to Table 1. In general, Enable P is a count–enable control: Enable T is both a count–enable and a Ripple–Carry Output control.

Table 1. Count Enable/Disable

Control Inputs			Result at Outputs	
Load	**Enable P**	**Enable T**	**Q0 – Q3**	**Ripple Carry Out**
H	H	H	Count	High when Q0–Q3 are maximum*
L	H	H	No Count	
X	L	H	No Count	High when Q0–Q3 are maximum*
X	X	L	No Count	L

* Q0 through Q3 are maximum when Q3 Q2 Q1 Q0 = 1111.

OUTPUT STATE DIAGRAMS



Binary Counters

SWITCHING WAVEFORMS

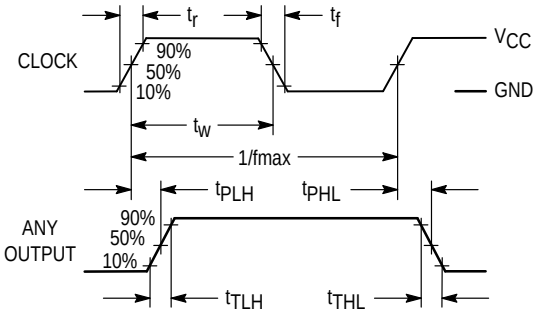


Figure 1.

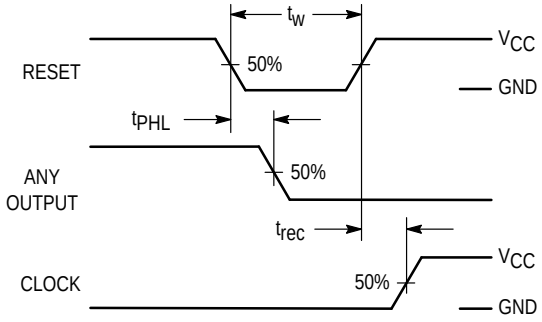


Figure 2.

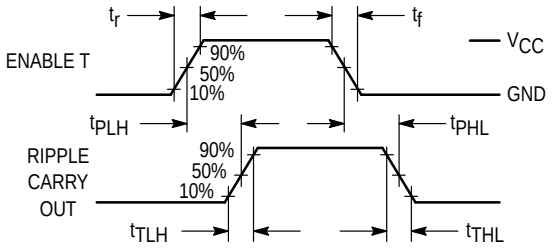


Figure 3.

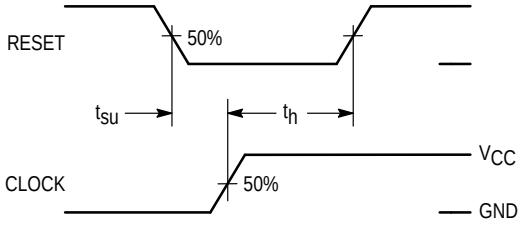


Figure 4. HC163A Only

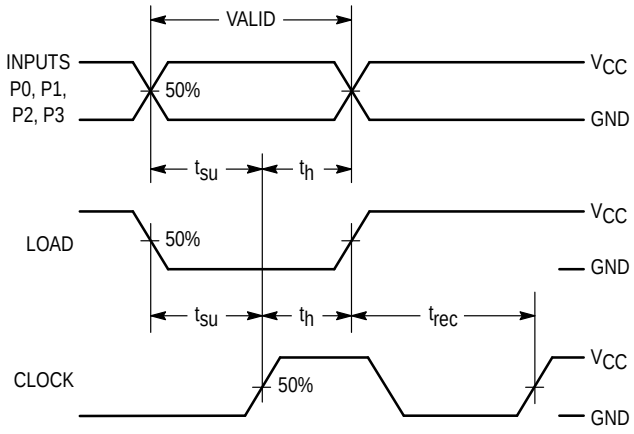


Figure 5.

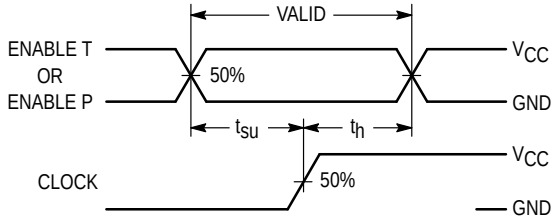
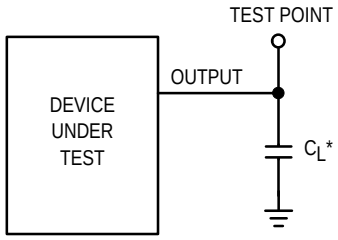


Figure 6.

TEST CIRCUIT



* Includes all probe and jig capacitance

Figure 7.

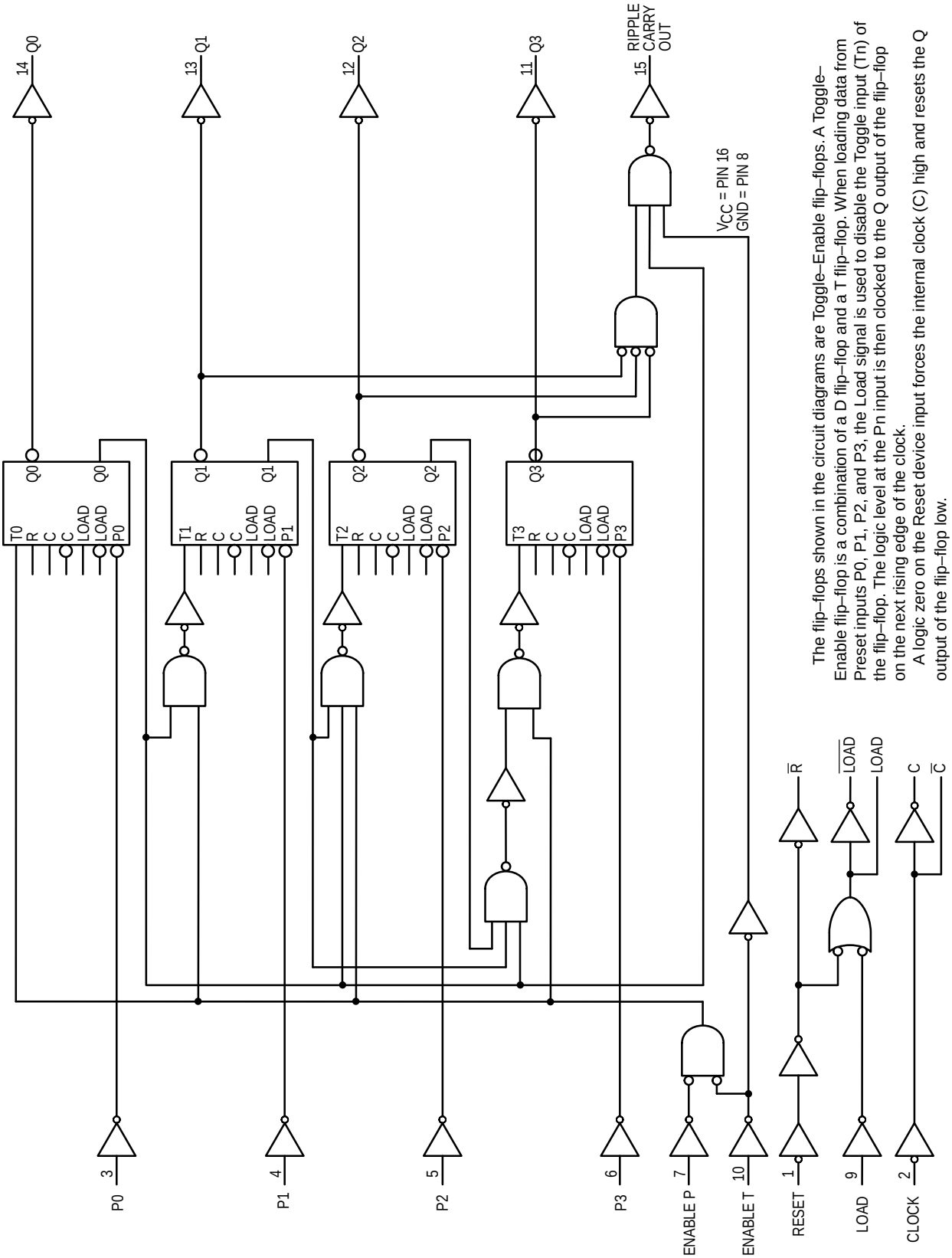


Figure 8. 4–Bit Binary Counter with Asynchronous Reset (MC54/74HC161A)

Sequence illustrated in waveforms:
1. Reset outputs to zero.
2. Preset to binary twelve.
3. Count to thirteen, fourteen, fifteen, zero, one and two.
4. Inhibit.

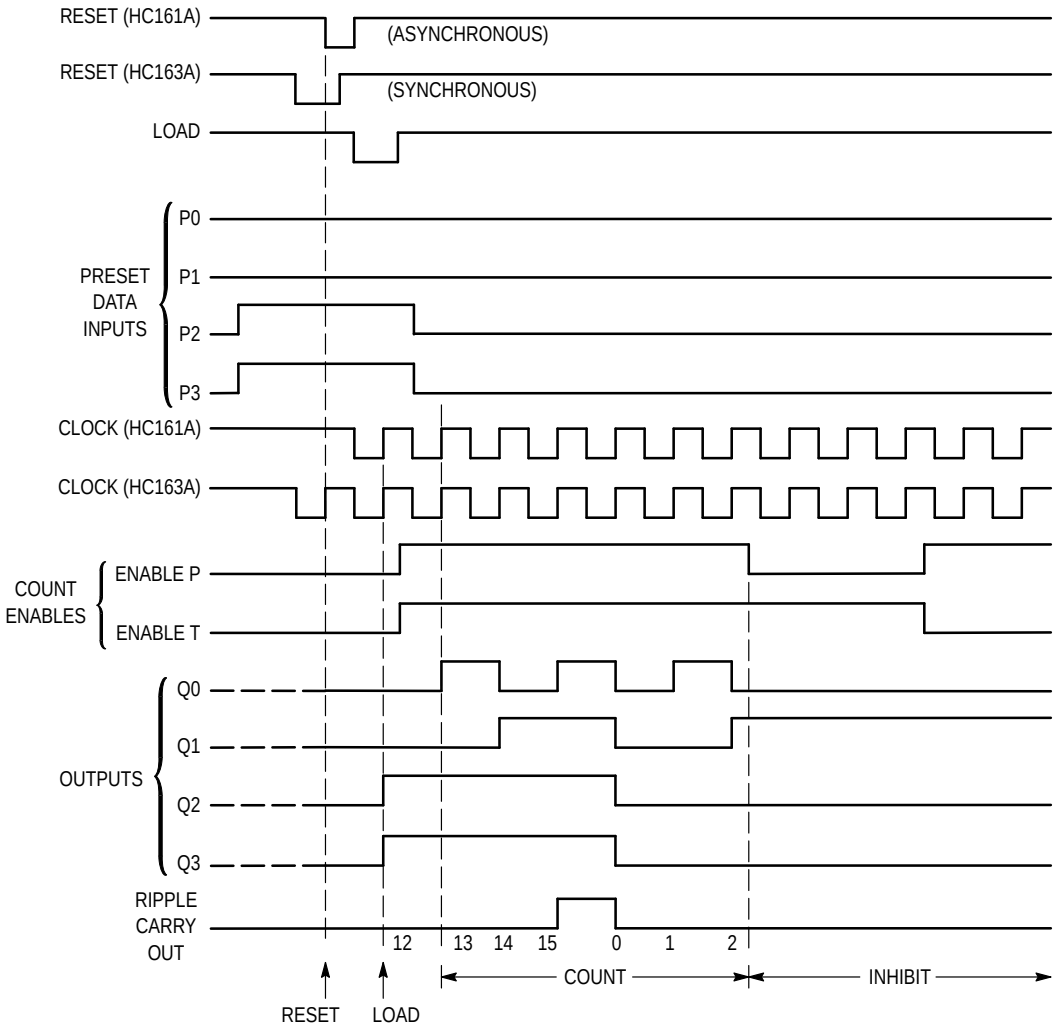


Figure 9. Timing Diagram

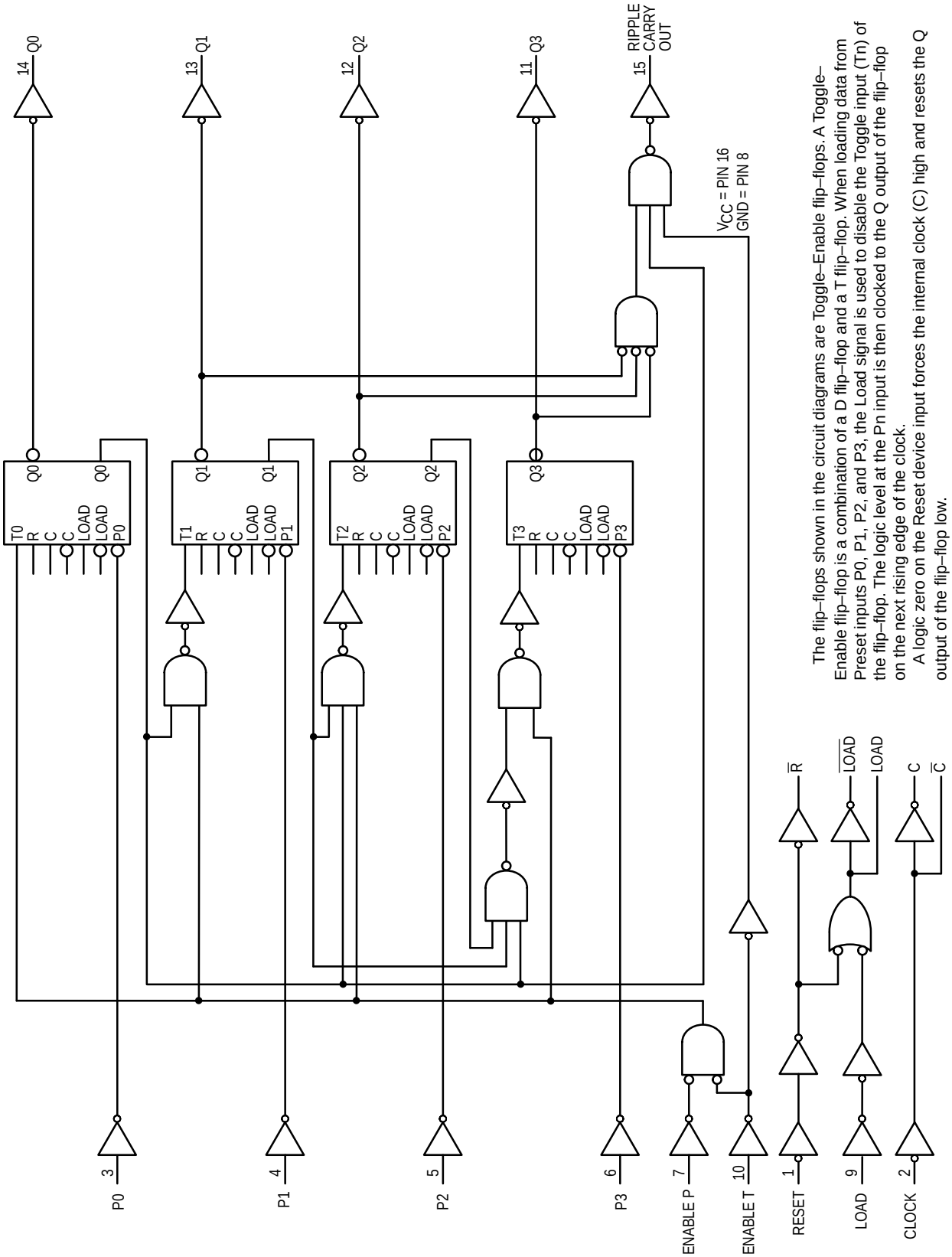
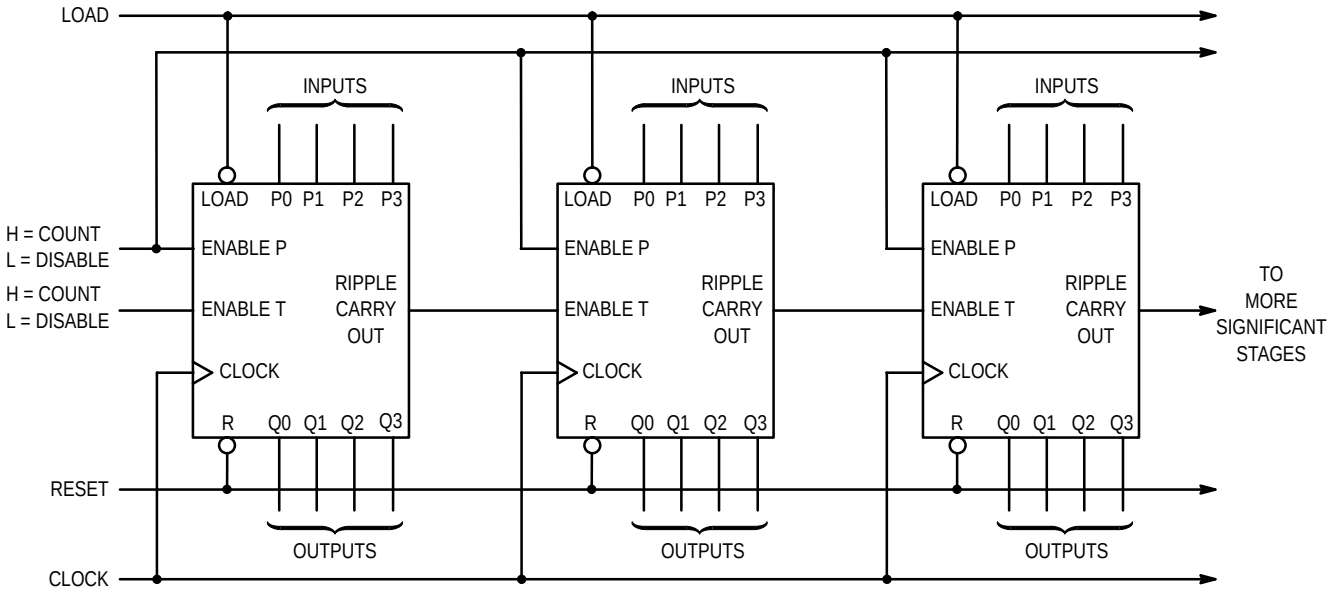


Figure 10. 4–Bit Binary Counter with Synchronous Reset (MC54/74HC163A)

TYPICAL APPLICATIONS CASCADING



NOTE: When used in these cascaded configurations the clock f_{max} guaranteed limits may not apply. Actual performance will depend on number of stages. This limitation is due to set up times between Enable (Port) and Clock.

Figure 11. N–Bit Synchronous Counters

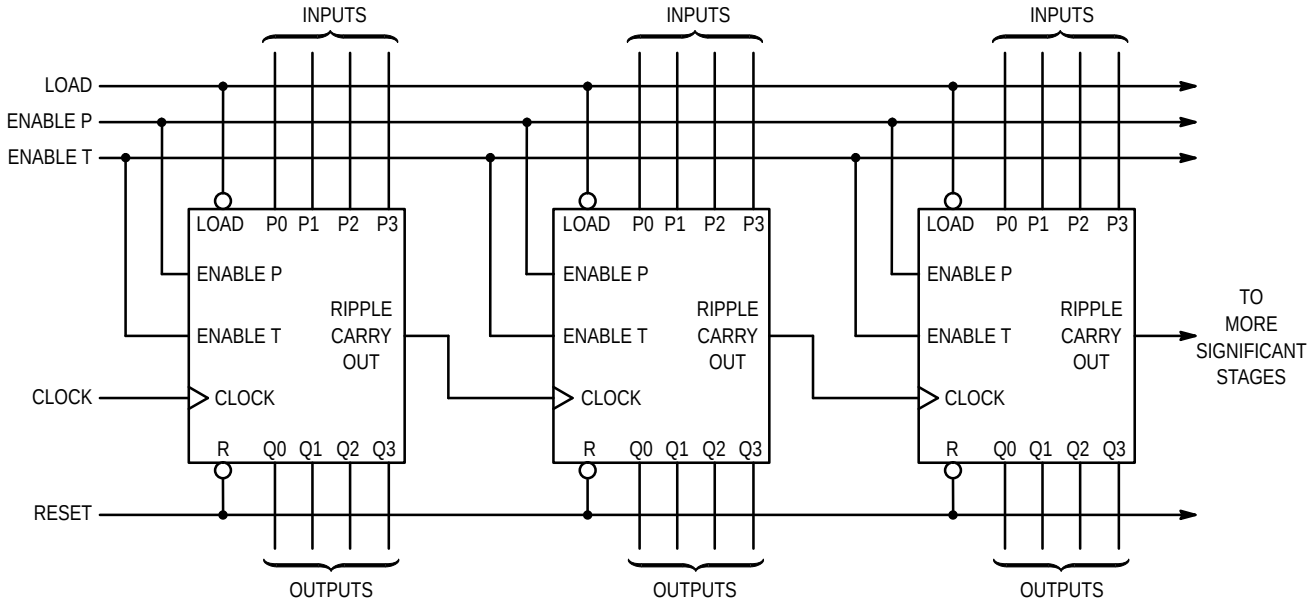


Figure 12. Nibble Ripple Counter

TYPICAL APPLICATIONS VARYING THE MODULUS

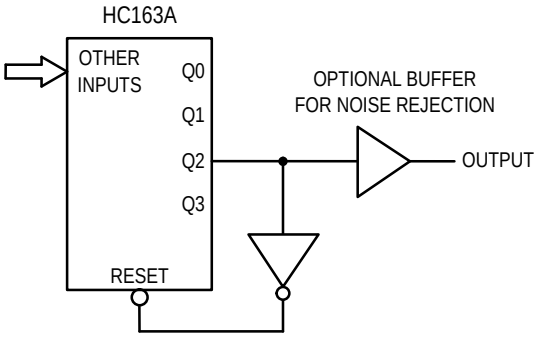


Figure 13. Modulo–5 Counter

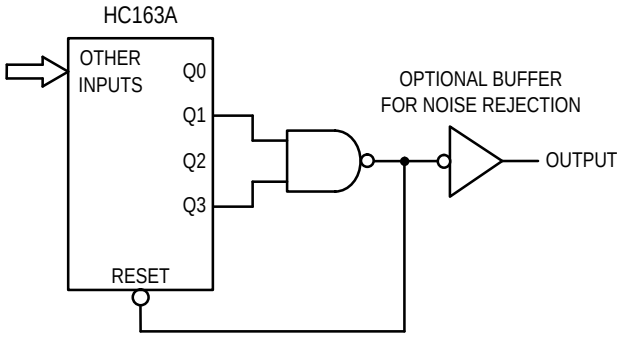
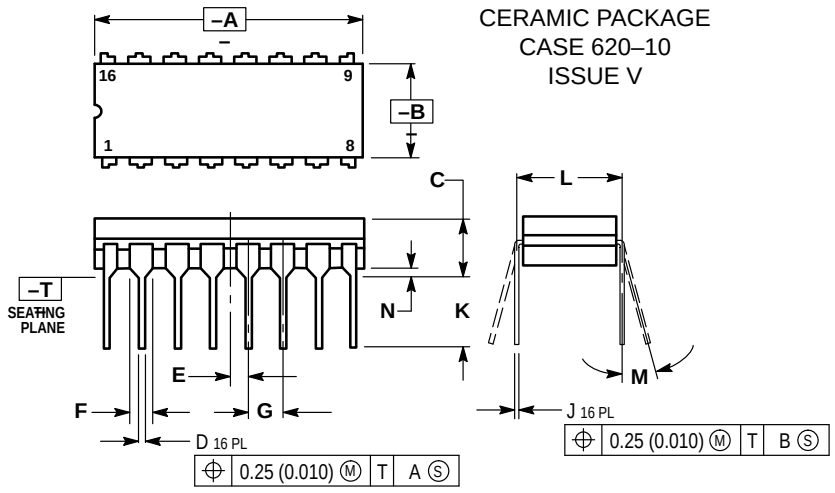


Figure 14. Modulo–11 Counter

The HC163A facilitates designing counters of any modulus with minimal external logic. The output is glitch–free due to the synchronous Reset.

OUTLINE DIMENSIONS

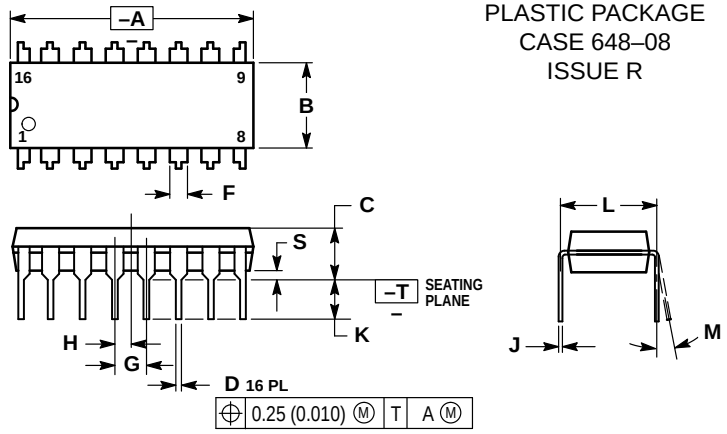
J SUFFIX
CERAMIC PACKAGE
CASE 620–10
ISSUE V



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

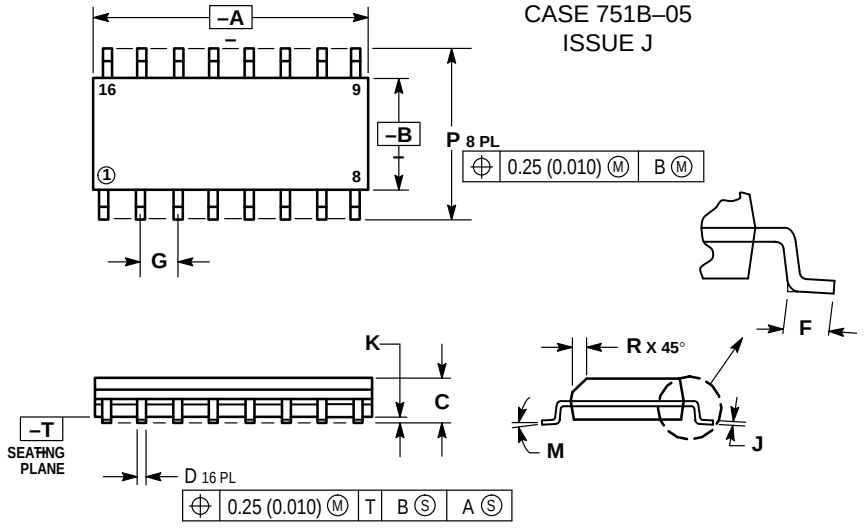
N SUFFIX
PLASTIC PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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